Preferred Device

Silicon Controlled Rectifiers

Reverse Blocking Thyristors

Designed primarily for half-wave ac control applications, such as motor controls, heating controls, and power supplies; or wherever half-wave, silicon gate-controlled devices are needed.

- Blocking Voltage to 800 Volts
- On–State Current Rating of 16 Amperes RMS
- High Surge Current Capability 160 Amperes
- Rugged Economical TO-220AB Package
- Glass Passivated Junctions for Reliability and Uniformity
- Minimum and Maximum Values of I_{GT}, V_{GT}, and I_H Specified for Ease of Design
- High Immunity to dv/dt 100 V/μsec Minimum at 125°C
- Device Marking: Logo, Device Type, e.g., MCR16N, Date Code

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off–State Voltage(1) (T _J = -40 to 125°C, Sine Wave, 50 to 60 Hz, Gate Open) MCR16N	VDRM, VRRM	800	Volts
On-State RMS Current (180° Conduction Angles; T _C = 80°C)	IT(RMS)	16	А
Peak Non-repetitive Surge Current (1/2 Cycle, Sine Wave 60 Hz, T _J = 125°C)	ITSM	160	A
Circuit Fusing Consideration (t = 8.3 ms)	l ² t	106	A ² sec
Forward Peak Gate Power (Pulse Width ≤ 1.0 μs, T _C = 80°C)	Рдм	5.0	Watts
Forward Average Gate Power (t = 8.3 ms, T _C = 80°C)	P _G (AV)	0.5	Watts
Forward Peak Gate Current (Pulse Width \leq 1.0 μ s, $T_C = 80$ °C)	I _{GM}	2.0	А
Operating Junction Temperature Range	TJ	-40 to +125	°C
Storage Temperature Range	T _{stg}	-40 to +150	°C

(1) V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.

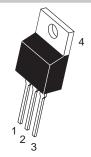


ON Semiconductor

http://onsemi.com

SCRs 16 AMPERES RMS 800 VOLT





TO-220AB CASE 221A STYLE 3

PIN ASSIGNMENT			
1	Cathode		
2	Anode		
3	Gate		
4	Anode		

ORDERING INFORMATION

Device	Package	Shipping
MCR16N	TO220AB	50 Units/Rail

Preferred devices are recommended choices for future use and best overall value.

THERMAL CHARACTERISTICS

Thermal Resistance — Junction to Case — Junction to Ambient	R _θ JC R _θ JA	1.5 62.5	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds	TL	260	°C

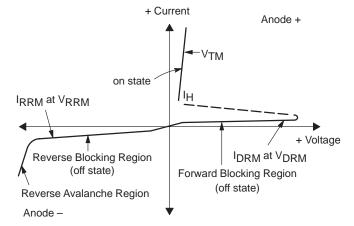
ELECTRICAL CHARACTERISTICS (T.j = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS	•				•
Peak Repetitive Forward or Reverse Blocking Current $T_J = 25^{\circ}C$ $(V_{AK} = Rated V_{DRM} \text{ or } V_{RRM}, \text{ Gate Open})$ $T_J = 125^{\circ}C$		_ -	_	0.01 2.0	mA
ON CHARACTERISTICS	•				•
Peak Forward On–State Voltage* (I _{TM} = 32 A)	VTM	_	_	1.7	Volts
Gate Trigger Current (Continuous dc) ($V_D = 12 \text{ V}, R_L = 100 \Omega$)	lgт	2.0	10	20	mA
Gate Trigger Voltage (Continuous dc) (V_D = 12 V, R_L = 100 Ω)	VGT	0.5	0.65	1.0	Volts
Hold Current (Anode Voltage = 12 V, Initiating Current = 200 mA, Gate Open)	lн	4.0	25	40	mA
Latch Current $(V_D = 12 \text{ V, } lg = 200 \text{ mA})$	IL		30	60	mA
DYNAMIC CHARACTERISTICS	•				
Critical Rate of Rise of Off–State Voltage (VD = Rated VDRM, Exponential Waveform, Gate Open, TJ = 125°C	dv/dt	100	300	_	V/µs
Critical Rate of Rise of On–State Current (IPK = 50 A, Pw = 30 µs, diG/dt = 1 A/µsec, Igt = 50 mA)	di/dt		_	50	A/μs

^{*}Indicates Pulse Test: Pulse Width ≤ 2.0 ms, Duty Cycle $\leq 2\%$.

Voltage Current Characteristic of SCR

Symbol	Parameter
VDRM	Peak Repetitive Off State Forward Voltage
IDRM	Peak Forward Blocking Current
VRRM	Peak Repetitive Off State Reverse Voltage
I _{RRM}	Peak Reverse Blocking Current
V_{TM}	Peak On State Voltage
lμ	Holding Current



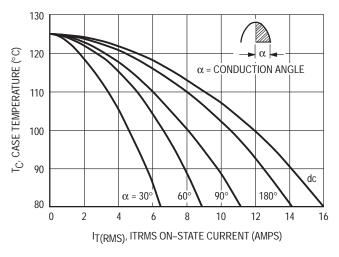


Figure 1. Typical RMS Current Derating

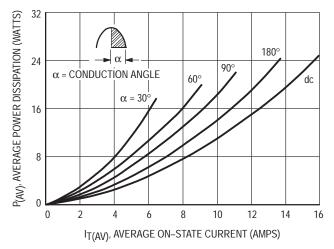


Figure 2. On State Power Dissipation

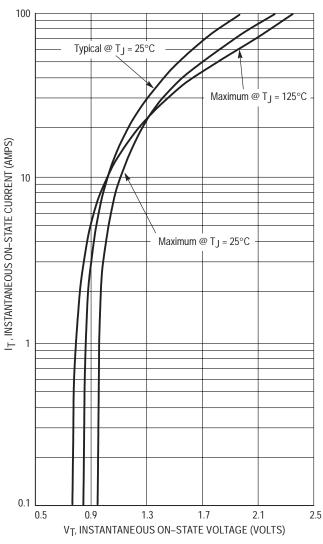


Figure 3. Typical On-State Characteristics

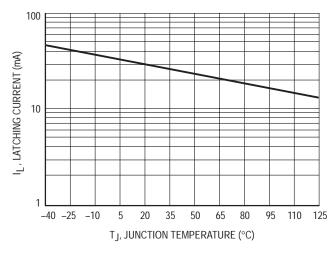


Figure 6. Typical Latching Current versus Junction Temperature

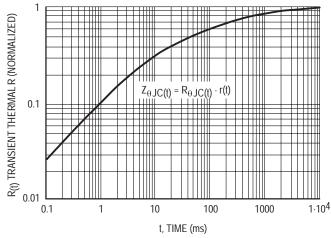


Figure 4. Transient Thermal Response

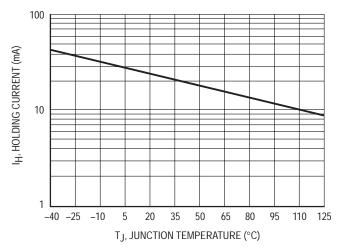


Figure 5. Typical Holding Current versus Junction Temperature

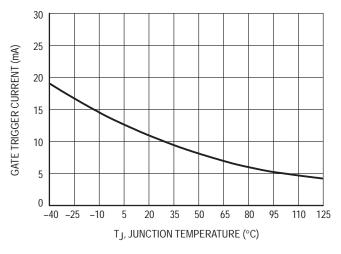


Figure 7. Typical Gate Trigger Current versus Junction Temperature

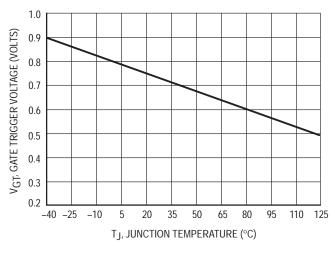


Figure 8. Typical Gate Trigger Voltage versus Junction Temperature

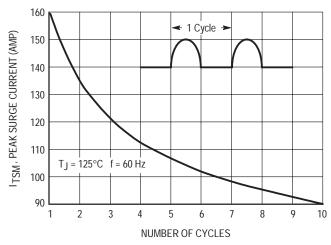
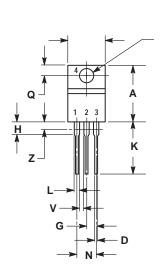
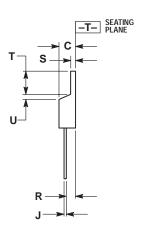


Figure 9. Maximum Non-Repetitive Surge Current

PACKAGE DIMENSIONS

TO-220AB CASE 221A-09 ISSUE Z





- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INC	INCHES MILLIMETER		IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.035	0.64	0.88
F	0.142	0.147	3.61	3.73
G	0.095	0.105	2.42	2.66
Н	0.110	0.155	2.80	3.93
J	0.018	0.025	0.46	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04

- STYLE 3:
 PIN 1. CATHODE
 2. ANODE
 3. GATE
 4. ANODE

Notes

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